

ABSTRACT

A substrate 6a having terminals 9 thereon is bonded to a wiring board 11 having output terminals 11c thereon through an ACF 20. The pitch P2 of the output terminals 11c is different from the pitch P1 of the terminals 9 taking into account deformation of the substrate 6a or the wiring board 11 during bonding. When the substrate 6a or the wiring board 11 deforms during the bonding, the both terminals are connected with the pitch P1' of the terminals 9 and the pitch P2' of the output terminals 11c becoming approximately equal to each other.